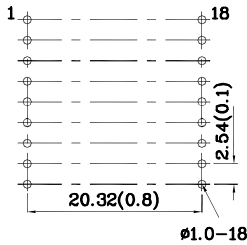


**Features**

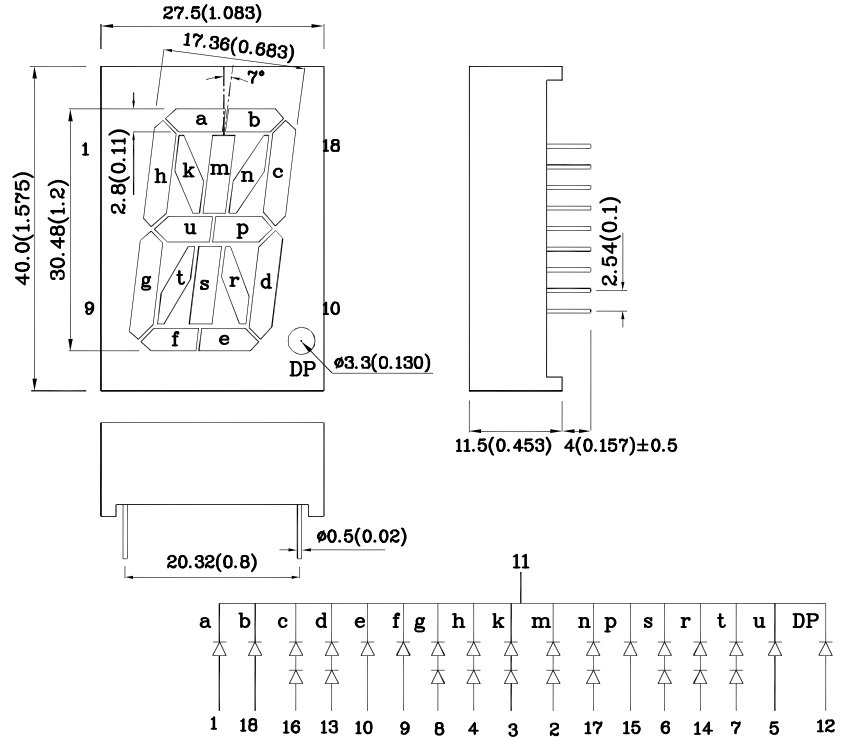
- Low power consumption
- Robust package
- I.C. Compatible
- Standard configuration: Gray face w/ white segments
- Optional black face provides superior color contrast
- RoHS Compliant



**RECOMMENDED PCB LAYOUT**



**Package Schematics**



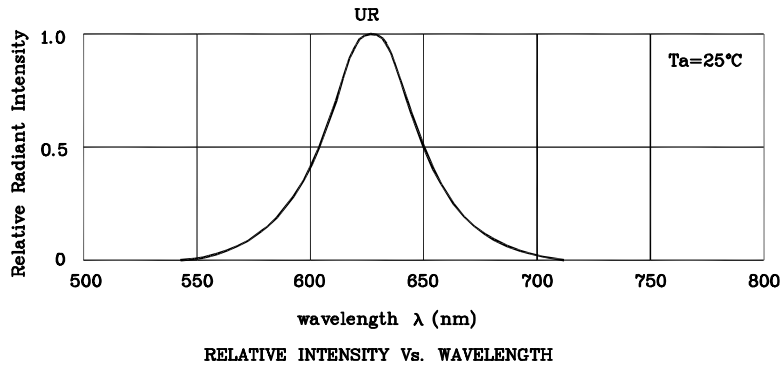
**Notes:**

1. All dimensions are in millimeters (inches), Tolerance is  $\pm 0.25(0.01)$  unless otherwise noted.
2. Specifications are subject to change without notice.

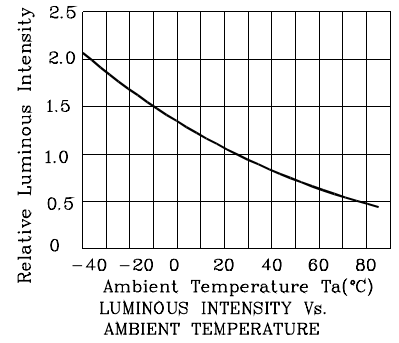
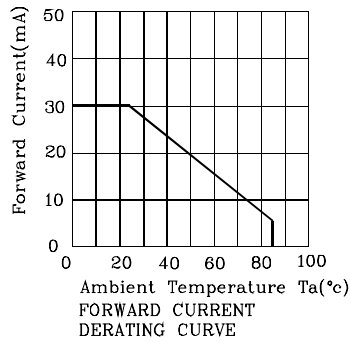
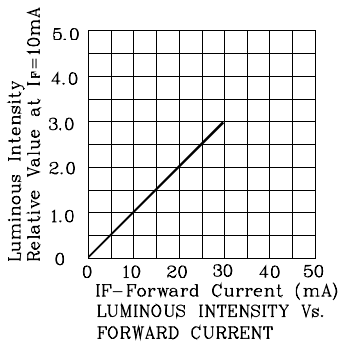
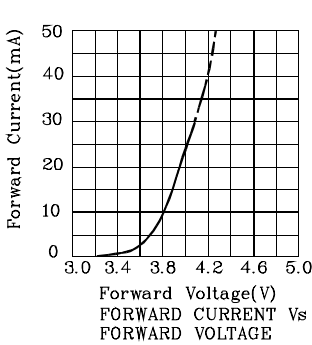
Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ )		UR (GaAsP/ GaP)	Unit
Reverse Voltage	c,d,g,h,k,m,n, s,r,t	VR	5
	a,b,e,f,p,u and DP		5
DC Forward Current	c,d,g,h,k,m,n, s,r,t	IF	30
	a,b,e,f,p,u and DP		30
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	c,d,g,h,k,m,n, s,r,t	iFS	160
	a,b,e,f,p,u and DP		160
Power Dissipation	c,d,g,h,k,m,n, s,r,t	PD	150
	a,b,e,f,p,u and DP		75
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3~5 Seconds		

Operating Characteristics ( $T_A=25^\circ\text{C}$ )		UR (GaAsP/ GaP)	Unit
Forward Voltage (Typ.) ( $I_F=10\text{mA}$ )	c,d,g,h,k,m,n, s,r,t	VF	3.8
	a,b,e,f,p,u and DP		1.9
Forward Voltage (Max.) ( $I_F=10\text{mA}$ )	c,d,g,h,k,m,n, s,r,t	VF	5
	a,b,e,f,p,u and DP		2.5
Reverse Current (Max.) ( $V_R=5\text{V}$ )	c,d,g,h,k,m,n, s,r,t	IR	10
	a,b,e,f,p,u and DP		10
Wavelength of Peak Emission (Typ.) ( $I_F=10\text{mA}$ )	$\lambda_P$	627	nm
Wavelength of Dominant Emission (Typ.) ( $I_F=10\text{mA}$ )	$\lambda_D$	625	nm
Spectral Line Full Width At Half- Maximum (Typ.)( $I_F=10\text{mA}$ )	$\Delta\lambda$	45	nm
Capacitance (Typ.) ( $V_F=0\text{V}$ , $f=1\text{MHz}$ )	C	15	pF

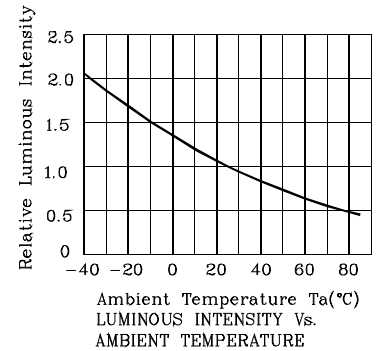
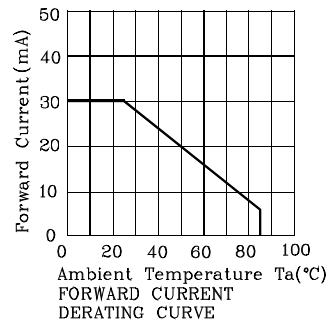
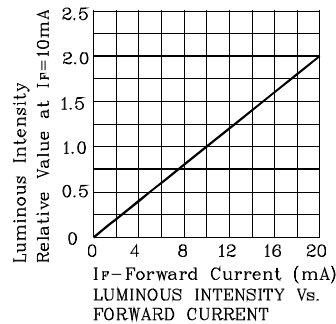
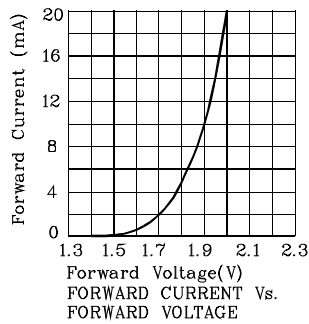
Part Number	Emitting Color	Emitting Material	Luminous Intensity (I <sub>F</sub> =10mA) ucd		Wavelength nm λP	Description
			min.	typ.		
XAUR30C	Red	GaAsP/GaP	3600	7490	627	Common Cathode, Rt. Hand Decimal.



❖ UR

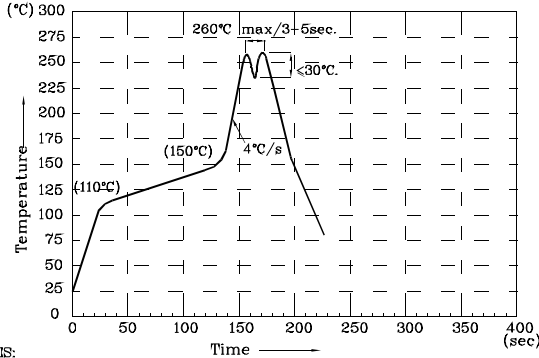


Note:the curves are on the segment c,d,g,h,k,m,n,s,r and t.



Note:the curves are on the segment a,b,e,f,p,u and DP.

Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. During wave soldering, the PCB top-surface temperature should be kept below 105°C.
5. No more than once.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

**PACKING & LABEL SPECIFICATIONS**

